Preface

Dear Distinguished Authors and Guests,

It was a great pleasure to welcome all participants in the 6th International Conference on Mechanical Structures and Smart Materials (ICMSSM), which was held on July 25-26, 2020 in Ho Chi Minh City, Vietnam.

The aim of ICMSSM2020 was to bring together experts from the academia and industry to present and discuss their research results and development in the areas of mechanical structures and smart materials. It provided opportunities for delegates to exchange new ideas and application experiences, and to establish collaborations.

The proceedings presented here comprise a selection of papers that were selected on the basis of originality, significance and relevance to the conference theme. The main conference themes and tracks are Mechanical Structures and Smart Materials and other related topics. Hopefully, all participants and other interested readers benefit scientifically from the proceedings and also find it stimulating in the process.

We would like to thank acknowledge the technical comments from the reviewers and thank all of the authors for their contributions to this proceeding book.

Finally, we wish all the authors and attendees of ICMSSM2020 productive and happy experience with this webinar conference.

With our warmest regards,
Organizing Committee
July 28, 2020

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